Materials Declaration

Package	LFCSP
Body Size	5 X 5 X 0.85
LeadCount	32
Option	Pb-free

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	85	1.90 E-02	323342
Epoxy Resin	10	2.24 E-03	38040
Phenol Resin	5	1.12 E-03	19020
Subtotal		2.24 E-02	380403

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	2.96 E-02	502119
Fe	2.35	7.12 E-04	12102
P	0.03	9.10 E-06	154
Zn	0.12	3.64 E-05	618
Subtotal		3.03 E-02	514994

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	5.80 E-04	9854

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	2.23 E-04	3781

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	7.61 E-04	12930

Chip

	% of Chip	Weight (g)	PPM
Si	100	3.93 E-03	66806

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	75	4.96 E-04	8424
Resin	25	1.65 E-04	2808
Subtotal		6.61 E-04	11231

Package Totals

Weight (g)	PPM
5.89 E-02	1000000

Molding Compound

Item	PPM	Method
Pb	Not Detected	EPA Method 3051A/3052. ICP-OES.
Cd	Not Detected	EPA Method 3051A/3052. ICP-OES.
Hg	Not Detected	EPA Method 3051A/3052. ICP-OES.
Cr+6	Not Detected	EPA Method 3060A & &196A. UV-VIS.
PBB	Not Detected	EPA Method 3540C/3550C. GC/MS.
PBDE	Not Detected	EPA Method 3540C/3550C. GC/MS.

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	EPA Method 3051A/3052. ICP-OES.
Cd	Not Detected	EPA Method 3051A/3052. ICP-OES.
Hg	Not Detected	EPA Method 3051A/3052. ICP-OES.
Cr+6	3	EPA Method 3060A & &196A. UV-VIS.
PBB	Not Detected	EPA Method 3540C/3550C. GC/MS.
PBDE	Not Detected	EPA Method 3540C/3550C. GC/MS.

Note: The information provided in this declaration are true to the best of ADI's knowledge
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to
any inaccuracy of such information.

ANALOG DEVICES

Materials Declaration

Package	LFCSP
Body Size	5 X 5 X0.85
LeadCount	32
Option	Sn/Pb

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	85	1.90 E-02	323342
Epoxy Resin	10	2.24 E-03	38040
Phenol Resin	5	1.12 E-03	19020
Subtotal		2.24 E-02	380403

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	2.96 E-02	502119
Fe	2.35	7.12 E-04	12102
P	0.03	9.10 E-06	154
Zn	0.12	3.64 E-05	618
Subtotal		3.03 E-02	514994

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	5.80 E-04	9854

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	1.89 E-04	3214
Pb	15	3.34 E-05	567
Subtotal		2.23 E-04	3781

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	7.61 E-04	12930

Chip

	% of Chip	Weight (g)	PPM
Si	100	3.93 E-03	66806

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	75	4.96 E-04	8424
Resin	25	1.65 E-04	2808
Subtotal		6.61 E-04	11231

Package Totals

Weight (g)	PPM
5.89 E-02	1000000

Molding Compound

Item	PPM	Method
Pb	Not Detected	EPA Method 3051A/3052. ICP-OES.
Cd	Not Detected	EPA Method 3051A/3052. ICP-OES.
Hg	Not Detected	EPA Method 3051A/3052. ICP-OES.
Cr+6	Not Detected	EPA Method 3060A & &196A. UV-VIS.
PBB	Not Detected	EPA Method 3540C/3550C. GC/MS.
PBDE	Not Detected	EPA Method 3540C/3550C. GC/MS.

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	EPA Method 3051A/3052. ICP-OES.
Cd	Not Detected	EPA Method 3051A/3052. ICP-OES.
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ANALOG DEVICES